

Abstract

Method for slicing wafers from a workpiece using a sawing wire

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The invention relates to a method for slicing wafers from a workpiece using a sawing wire, wherein at least two wire guide rolls clamp a wire web. Each wire guide roll has a multiplicity of grooves in its lateral surface, wherein at least one groove in which no wire is inserted during the wire sawing is present alongside a wire-guiding groove and, after the wear of the wire-guiding grooves or after a defined number of sawing processes, the sawing wire is wound over into the previously unoccupied grooves that are not yet worn or used, respectively.

15

Fig. 2b